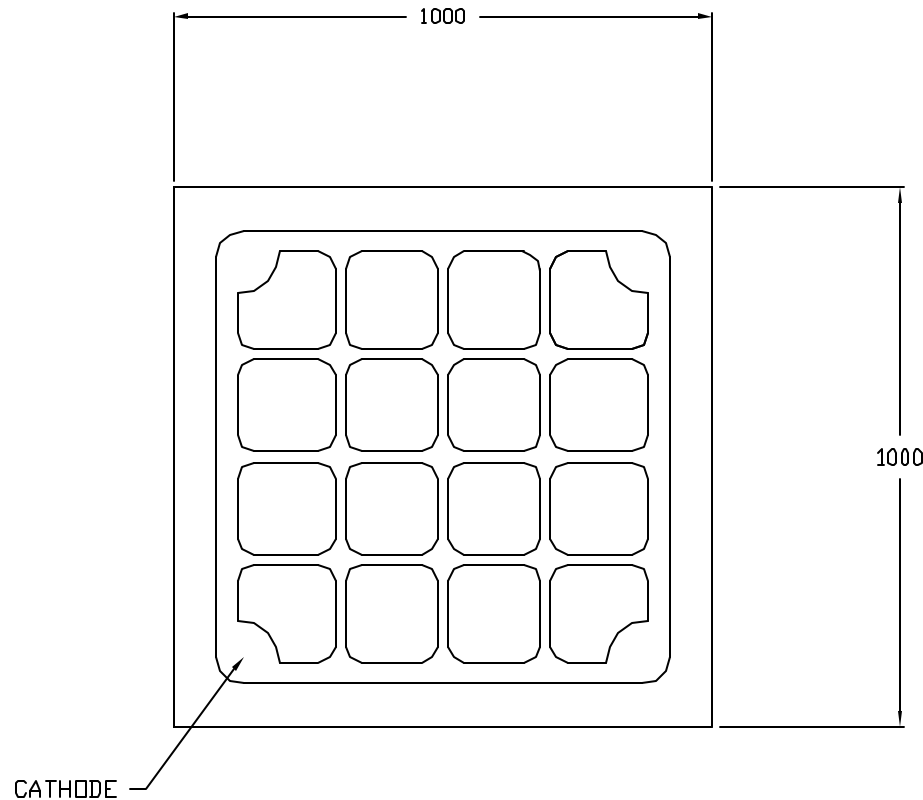


PART NUMBER
SSD-LX040E690DGNU

REV.



ELECTRO-OPTICAL CHARACTERISTICS $T_{amb} = 25^{\circ}\text{C}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH	680	690	700	nm	$I_f = 20\text{mA}$
FORWARD VOLTAGE		1.7	1.9	V	$I_f = 20\text{mA}$
FORWARD VOLTAGE		1.9	2.3	V	$I_f = 350\text{mA}$
REVERSE VOLTAGE	5			mW	$I_r = 10\mu\text{A}$
RADIANT POWER	1.4	1.9		mW	$I_f = 20\text{mA}$
RADIANT POWER		60		mW	$I_f = 350\text{mA}$
RADIANT POWER		100		mW	$I_f = 700\text{mA}$
SPECTRAL BANDWIDTH AT 50%		22		nm	
SWITCHING TIME		50		ns	

NOTES:

1. UNITS: μm
2. TYPICAL THICKNESS= $150 \pm 25\mu\text{m}$
3. WIREBOND METALIZATION: GOLD

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.038), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (0.002), LEAD LENGTH=±0.75 (±0.030). MIN= +DECIMAL PRECISION MAX= +0.00 -0.00

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1 mm x 1mm 690 nm HIGH POWER CHIP
GOLD BOND PAD, N. SIDE UP

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RELIABILITY NOTE

OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.



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